

# Automotive Dual N-Channel 40 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY	
V <sub>DS</sub> (V)	40
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0093
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0111
I <sub>D</sub> (A) per leg	30
Configuration	Dual

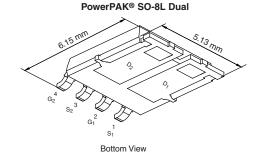
## **FEATURES**

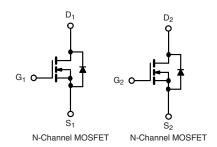
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- AEC-Q101 Qualifiedd
- Material categorization:
  For definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>





ROHS COMPLIANT HALOGEN FREE





ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SQJ912AEP-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	s otherwise noted	)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V <sub>DS</sub>	40	V
Gate-Source Voltage		$V_{GS}$	± 20	V
Continuous Drain Currenta	T <sub>C</sub> = 25 °C	1	30	
Continuous Drain Current-	T <sub>C</sub> = 125 °C	I <sub>D</sub>	29	
Continuous Source Current (Diode Conduction	on) <sup>a</sup>	I <sub>S</sub>	30	Α
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	120	
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	26	
Single Pulse Avalanche Energy	L = U. I IIII	E <sub>AS</sub>	34	mJ
Martin or Brown Biotheritash	T <sub>C</sub> = 25 °C	P <sub>D</sub>	48	W
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 125 °C	16		
Operating Junction and Storage Temperature	Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C
Soldering Recommendations (Peak Tempera	ture) <sup>e, f</sup>		260	C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	$R_{thJA}$	85	°C/W
Junction-to-Case (Drain)		$R_{thJC}$	3.1	C/VV

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. When mounted on 1" square PCB (FR4 material).
- d. Parametric verification ongoing.
- e. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static	•				•	l	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	40	-	-	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	0 V, V <sub>GS</sub> = ± 20 V	1	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 40 V	-	-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		$V_{GS} = 0 V$	V <sub>DS</sub> = 40 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 9.7 A	-	0.0077	0.0093	
Drain Course On State Besistance	В	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 8.9 A	-	0.0093	0.0111	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 9.7 A, T <sub>J</sub> = 125 °C	-	-	0.0138	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 9.7 A, T <sub>J</sub> = 175 °C	-	-	0.0169	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	$V_{DS}$	= 15 V, I <sub>D</sub> = 10 A	-	58	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	1438	1835	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	-	217	271	рF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	91	114	
Total Gate Charge <sup>c</sup>	Qg			-	25.6	38	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 20 \text{ V}, I_{D} = 11.3 \text{ A}$	=	4	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	4	-	
Gate Resistance	$R_g$	f = 1 MHz		0.72	1.44	2.2	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	10	15	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_{L} = 20 \Omega$		-	9	14	ne
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 1 \text{ A}, Y$	$V_{\rm GEN} = 10  \text{V},  \text{R}_{\rm g} = 1  \Omega$	=	23	35	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			-	11	17	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			=	-	120	Α
Forward Voltage	$V_{SD}$	I	6.5 A, V <sub>GS</sub> = 0 V	1	0.8	1.1	V

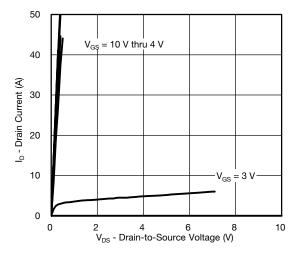
#### **Notes**

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

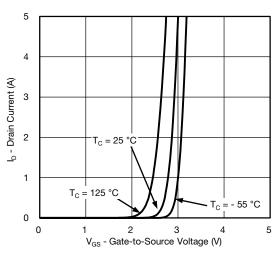
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



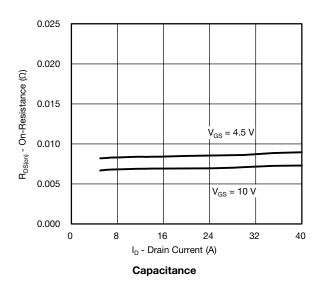
# **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

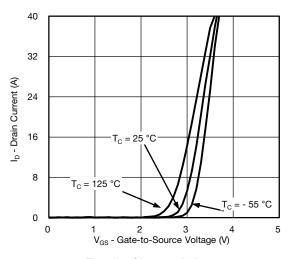


#### **Output Characteristics**

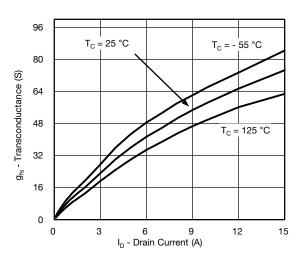


# Transfer Characteristics

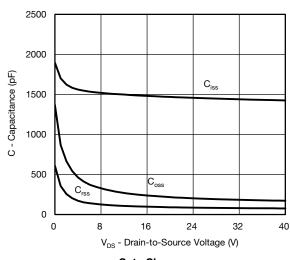




#### **Transfer Characteristics**

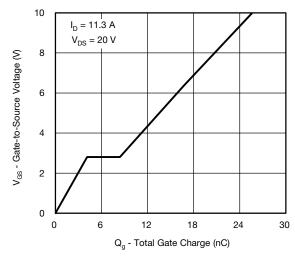


#### Transconductance

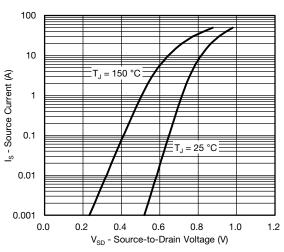




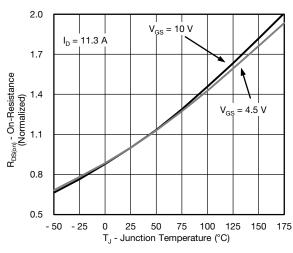
# **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



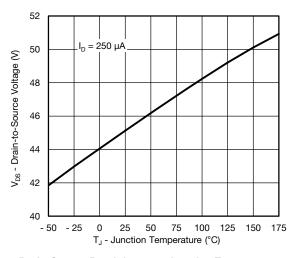
#### **Gate Charge**



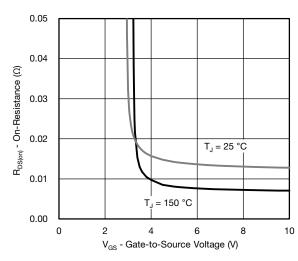
# Source Drain Diode Forward Voltage



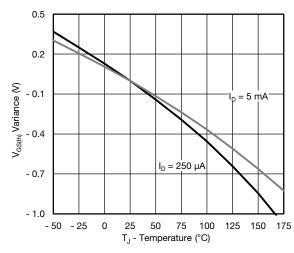
On-Resistance vs. Junction Temperature



# **Drain-Source Breakdown vs. Junction Temperature**



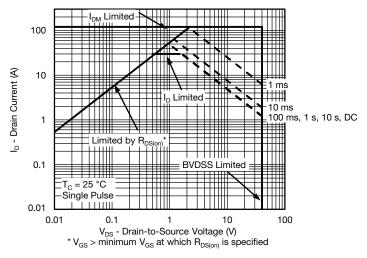
### On-Resistance vs. Gate-to-Source Voltage



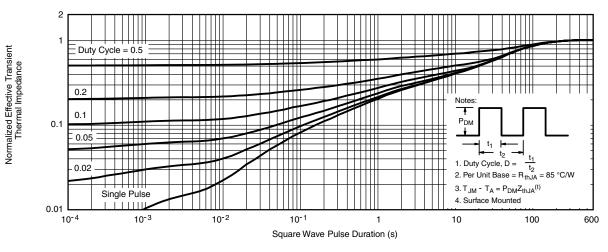
Threshold Voltage



# **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



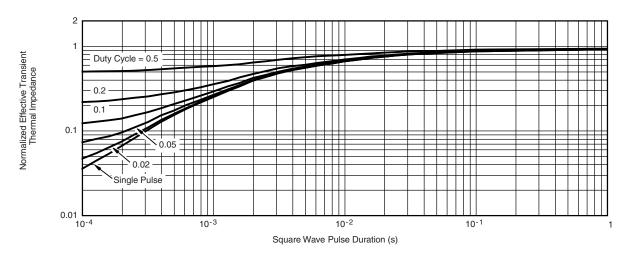
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



# **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



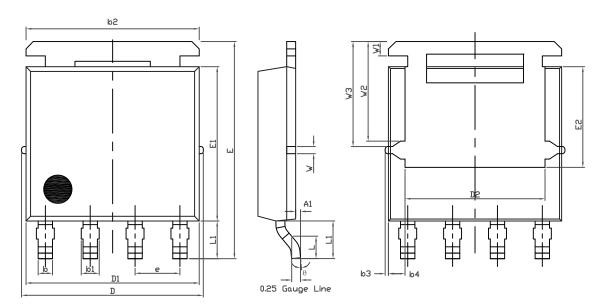
### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

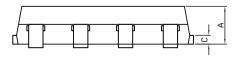
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

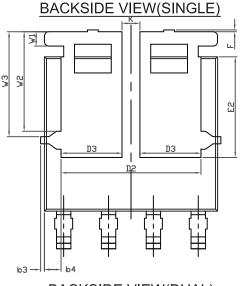
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# PowerPAK® SO-8L Case Outline for Al Parts



**TOPSIDE VIEW** 





BACKSIDE VIEW(DUAL)



DIM	MILLIMETERS			INCHES				
DIM.	MIN.	NOM.	MAX.	MIN. NOM.		MAX. MIN. NOM.		MAX
Α	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3		0.094			0.004			
b4		0.47			0.019			
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е		1.27 BSC		0.050 BSC				
Е	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	2.75	2.85	2.95	0.108	0.112	0.116		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
K		0.51			0.020			
W	0.23			0.009				
W1	0.41			0.016				
W2	2.82			0.111				
W3		2.96			0.117			
q	0°	-	10°	0°	-	10°		

ECN: C15-1203-Rev. A, 07-Sep-15

DWG: 6044

## Note

· Millimeters will gover



# RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)



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Vishay

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